### INTEGRATED CIRCUITS

DATA SHEET



Product specification File under Integrated Circuits, IC11 1996 May 06



### TDA5149G

#### FEATURES

#### **General features**

- Single-chip voice coil motor driver and spindle motor pre-driver
- Internal voltage reference generator
- Programming of timing parameters via the serial bus
- Control of sleep, brake and disable modes for both the VCM and spindle via the serial bus
- Temperature monitor circuit
- General purpose uncommitted operational amplifier.

#### Voice coil motor driver

- On-board full-bridge power DMOS driver with low R<sub>DSon</sub>
- · Class AB linear amplifier with no dead zone
- Adjustable gain and bandwidth
- Retract circuit operating at power-down.

#### Spindle motor pre-driver

- Designed to drive external N-channel power MOSFETs for brushless, sensorless DC motors
- Internal or external commutation control
- Digital commutation timing
- Average motor supply current control with Pulse Width Modulation (PWM)
- Soft switching under PWM control
- Spindle brake after park at power-down.

#### APPLICATIONS

• 12 V high-performance hard disk drives.

#### GENERAL DESCRIPTION

The TDA5149G is a combination of a voice coil motor driver and a spindle motor pre-driver, capable of operating 12 V high-performance hard disk drives.

The device integrates a spindle pre-driver that drives three external N-channel power MOSFETs in order to drive a three-phase brushless, sensorless DC motor in full wave mode. In the normal mode, commutations are generated from the internal Back EMF (BEMF) sensing circuitry. Commutations, however, can also be generated from an external source, thereby providing the possibility of driving the motor in the stepper-motor mode.

The VCM driver is a linear transconductance amplifier capable of handling currents up to 1.65 A. It allows external adjustment of the gain and compensation. The TDA5149G also contains two drivers for a latch that secures the heads in the event of power-down.

To control functions such as park, brake, sleep or disable and to program the different timing parameters, the TDA5149G is provided with a three-wire serial port. A high precision voltage monitor is also included, for both 5 and 12 V power supplies. Finally, the IC contains a temperature monitor circuit and an uncommitted operational amplifier connected to  $V_{DD}$ , which can be used freely within the application. The device is contained in a LQFP64 package with 4 pins connected to the lead frame for improved heat dissipation.

#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>DD</sub>	general supply voltage (pin 54)		10.8	12.0	13.2	V
V <sub>DDD</sub>	digital supply voltage (pin 55)		4.5	5.0	5.5	V
V <sub>DDA1</sub>	analog supply voltage (pin 27)		4.5	5.0	5.5	V
I <sub>oVCM</sub>	voice coil motor output current		-	-	1.65	A
R <sub>DSon</sub>	VCM power DMOS total on-resistance	T <sub>j</sub> = 25 °C	-	-	0.65	Ω
	(including leads and bond wires)	T <sub>j</sub> = 125 °C	-	-	1.1	Ω

#### ORDERING INFORMATION

TYPE		PACKAGE			
NUMBER	NAME	DESCRIPTION	VERSION		
TDA5149G	LQFP64	FP64 plastic low profile quad flat package; 64 leads; body $10 \times 10 \times 1.4$ mm SOT314-2			

#### **BLOCK DIAGRAMS**





#### PINNING

SYMBOL	PIN	I/O	DESCRIPTION	
CAPY	1	I/O	charge pump capacitor	
MOT0	2	1	motor centre tap input	
H1	3	0	driver output to gate of upper power FET 1	
MOT1	4	I	back EMF comparator input 1	
L1	5	0	driver output to gate of lower power FET 1	
H2	6	0	driver output to gate of upper power FET 2	
MOT2	7	I	back EMF comparator input 2	
L2	8	0	driver output to gate of lower power FET 2	
H3	9	0	driver output to gate of upper power FET 3	
МОТ3	10	1	back EMF comparator input 3	
L3	11	0	driver output to gate of lower power FET 3	
IDRIVE	12	I	adjustment for output stage drive current	
SPINSENSEH	13	I	positive spindle sense amplifier input	
SPINSENSEL	14	1	negative spindle sense amplifier input	
SISENS	15	0	spindle sense amplifier output	
AGND	16	_	general analog ground; note 1	
I <sub>ref</sub>	17	0	reference current generator output	
SINTIN	18	1	negative integrator input	
ISPIN	19	1	positive integrator input, average current adjustment	
SICOMP	20	0	integrator output	
RPOS	21	1	duty cycle modulator input	
CSS1	22	I/O	soft switching capacitor 1	
CSS2	23	I/O	soft switching capacitor 2	
STOSC	24	I/O	sawtooth oscillator capacitor	
SCANOUT	25	0	test output	
POR <sub>DELAY</sub>	26	I/O	power-on reset delay capacitor (active LOW)	
V <sub>DDA1</sub>	27	_	analog supply voltage 1 (+5 V)	
POR5 <sub>ADJ</sub>	28	0	adjustment of POR threshold (for +5 V)	
POR12 <sub>ADJ</sub>	29	0	adjustment of POR threshold (for +12 V)	
AMPIN-	30	1	negative input of the uncommitted operational amplifier	
AMPIN+	31	1	positive input of the uncommitted operational amplifier	
PGND1	32	_	power ground 1 for VCM DMOS; note 1	
AMPOUT	33	0	uncommitted operational amplifier output	
RESETP	34	0	power-on reset digital output with passive pull-up resistor	
RESETA	35	0	power-on reset digital output with active pull-up resistor	
V <sub>CM</sub>	36	0	negative output voltage of the VCM power stage	
TEMPMON	37	0	temperature monitor output	
CLAMP	38	I/O	clamp capacitor used for head retraction	
V <sub>DDV</sub>	39	_	power supply for VCM DMOS driver (+12 V)	
V <sub>CMIN2</sub>	40	1	switchable VCM control input voltage	

SYMBOL	PIN	I/O	DESCRIPTION	
V <sub>CMIN1</sub>	41	I	VCM control input voltage	
V <sub>CMSENSEH</sub>	42	I	positive VCM sense amplifier input voltage	
V <sub>CMSENSEL</sub>	43	I	negative VCM sense amplifier input voltage	
V <sub>CM+</sub>	44	0	positive output voltage of the VCM power stage	
H0	45	0	gate control of the isolating power FET	
VCM <sub>ref</sub>	46	1	reference voltage input for the VCM	
BRAKEPOWER	47	I/O	reservoir capacitor for the brake/park circuitry	
PGND2	48	-	power ground 2 for VCM DMOS; note 1	
V <sub>ref(o)</sub>	49	0	reference voltage generator output	
V <sub>CMSENSOUT</sub>	50	0	VCM sense amplifier output voltage	
BRAKEDELAY	51	I/O	powerless brake delay adjustment	
LATCHHOLD	52	0	latch hold output	
LATCHACTIV	53	0	latch activate output	
V <sub>DD</sub>	54	-	general supply voltage (+12 V)	
V <sub>DDD</sub>	55	-	digital supply voltage (+5 V)	
SCANTEST	56	I	test mode input	
FG	57	0	commutation frequency generator output	
CLOCK	58	I	clock for digital timing input	
SDATA	59	I	serial port data input	
SCLOCK	60	I	serial port clock input	
SENABLE	61	I	serial port enable input	
CAPX2	62	I/O	charge pump capacitor input/output	
CAPX1	63	I/O	charge pump capacitor input/output	
DGND	64	_	digital ground; note 1	

#### Note

1. The 4 ground pins are tied to the lead frame for better heat dissipation.



### TDA5149G

## 12 V Voice Coil Motor (VCM) driver and spindle motor pre-driver combination chip

#### FUNCTIONAL DESCRIPTION

#### Spindle

The spindle section contains both the low and high side pre-drivers for a three phase DC brushless motor. The digital commutation control, using the timing information provided via the serial port, is responsible for the proper switch-on and switch-off of the external power FETs. It is also responsible for selecting the correct BEMF comparator.

For optimum power efficiency, a continuous PWM method is used to control the average current from the power supply to the motor coils. This PWM mode, by controlling the average power supply current, produces a lower torque ripple and thus lower audible noise. In order to reduce further acoustic noise the TDA5149G is provided with a soft switching circuit to turn-on and turn-off linearly the switching current under PWM control. The switching transition time is controlled by the digital commutation circuit and is fixed to 50% of the time between two zero-crossings, i.e. 30° of the electrical revolution.

Soft switching is achieved by activating, during commutation, a free-running duty-cycle modulator controlled by a linearly decreasing voltage across a capacitor. This will reduce the current smoothly in the off-going leg to zero. In conjunction with this additional PWM open loop, the average current control regulates the sum of the current in the off-going and on-going leg.

This method requires two PWM control loops; one to control the average current (main loop) and one to control the current in the off-going leg. The swapping of the two loops is realized with a pair of analog switches that are sequentially switched by the digital commutation circuitry.

The PWM control also causes PWM pulses on the back EMF. These pulses disturb correct sensing of the back EMF for the zero-crossing detection. Consequently, edge-triggered latches are inserted behind the back EMF comparators, thus ensuring reliable back EMF sensing.

In the SPINMODE, programmable via the serial bus, the user can feed their own commutation pulses to the pre-drivers and control the motor in the stepper-motor mode. The commutation pulses are applied to the TDA5149G via the serial bus by setting the COMMCLK bit successively to logic 1 and logic 0.

The different control modes of the TDA5149G can be commanded via the serial bus. These modes are as follows:

- Sleep mode: all analog circuits, except the power supply monitor, are switched off to reduce the power consumption of both the 12 and 5 V supplies.
- Disable mode: the output voltage of all pre-drivers is LOW thus the external power MOSFETs are not conducting.
- Brake mode: all low side pre-drivers are turned on (output voltage HIGH) thus switching on the low-side power MOSFETs. In this way the back EMF voltage of the motor is short-circuited to ground.

#### Voice coil motor

The VCM is a linear, symmetrical, class AB, H-bridge type power amplifier with all power devices on-chip. The driver is a transconductance amplifier that controls the output currents up to 1.65 A. The driver is constructed in a master-slave configuration with the zero current level internally adjusted in such a way that it corresponds to the middle of the output swing. Moreover, the gain of the slave has been made greater than 1 in order to ensure full saturation of the driver output VCM+.

The gain of the closed loop is programmable, using the  $V_{GAINSEL}$  bit. This bit can be programmed via the serial bus. A sense resistor (R<sub>s</sub>) allows the measurement of the VCM current. The voltage across this resistor is connected to an accurate sense amplifier with a typical gain of 5. The output of the sense amplifier ( $V_{CMSENSOUT}$ ) is fed back to the input of the VCM amplifier. Because of the symmetry of the circuit, the compensation network can be connected between the VCM1 input and the VCM– output.

Control modes such as VCM-BRAKE, VCM-DISABLE and VCM-PARK can be controlled via the serial bus.

#### Latch drivers

The TDA5149G provides the possibility of driving an external latch to secure the VCM heads. There are two modes; the activate mode (LACTIVE) and the hold mode (LHOLD). The hold mode is used to preserve power. Both modes are controlled via the serial bus. The drivers are switched off during the SLEEP mode or in the event of a power-down.

#### Power-on/power-off reset

The power-on reset circuitry monitors the analog, digital and general supplies. The voltage thresholds have been set internally for both supplies, i.e. 4.4 V for V<sub>DDA</sub> and V<sub>DDD</sub>, and 10.5 V for V<sub>DD</sub>. External adjustment and filtering, to suppress supply spikes, has been made possible through the pins  $POR5_{ADJ}$  and  $\overline{POR12}_{ADJ}$ .

When either of the supplies falls below their threshold levels, the reset circuit provides two active LOW output signals. The RESETA signal is a full CMOS output and the RESETP signal has an active pull-down MOS transistor with a passive pull-up resistance of 10 k $\Omega$ . The latter can be used for emulation purposes. Both signals remain LOW until the supply voltages are again above the threshold level, delayed by a time constant period that is determined by the value of the capacitor connected to pin POR<sub>DELAY</sub>.

A park sequence is initiated on a reset fault. This includes disabling the actuator latch drivers and starting a delayed spindle brake operation by switching on the low side pre-drivers simultaneously. This brake delay is determined by an external RC combination connected to BRAKEDELAY. Actuator PARK and spindle BRAKE can also be controlled via the serial port.

At power-up, the two reset output signals (RESETA and RESETP) will remain LOW as long as either supply voltage is below the specified threshold plus the hysteresis voltage. Once the supply voltages are above their specific trip levels, the two reset signals become HIGH after the power-on reset delay ( $\overline{POR}_{DELAY}$ ). This delay time is determined by the value of the capacitor connected to the  $\overline{POR}_{DELAY}$  pin.

#### Powerless park/brake

As with the normal retract procedure, an actuator park sequence is initiated whenever a power-down situation occurs. The power-on/power-off reset circuit generates the two active LOW reset signals and also activates the VCM park circuit. The VCM park circuit provides a voltage, retrieved from the rectified back EMF voltage of the running-out spindle, of 1.2 V (typ.) to the VCM pin. The voltage at pin VCM+ is 0 V. This voltage is supplied by the capacitor  $C_{CLAMP}$  that is connected to the CLAMP pin. This capacitor smooths the rectified back EMF and stores the electrical energy generated by the motor.

To ensure that the stored energy in the clamp capacitor is only used for the park operation, the CLAMP input must be isolated from the power supply. This can be achieved by using a Schottky diode or a reverse connected N-channel power FET (see Fig.1). The TDA5149G provides an output H0 to control this power FET.

At power-down the brake delay circuit is also enabled. The brake delay circuit is supplied by the energy stored in the capacitor (charged during normal operation from  $V_{DD}$ ) that is connected to the BRAKEPOWER pin. Both the BRAKEDELAY and BRAKEPOWER pins are then isolated from the 12 V supply voltage. When the voltage on the BRAKEDELAY pin reaches a value of 1.6 V (typ.), the low-side external power FETs are turned on to brake the spindle motor. The BRAKEPOWER capacitor then supplies the current to keep the power FETs conducting. This means that the voltage on this capacitor decreases with time.

#### Serial port

The serial port is used to modify the various operational modes of the TDA5149G and to adjust the timing parameters to ensure the proper commutation sequence of the spindle motor. It is a synchronous, slave only, three-wire communication port with data (SDATA), clock (SCLOCK) and enable (SENABLE) inputs.

The serial port requires the data to be sent in bytes, the LSB (data 0) to be sent first and the MSB (address 2) last. The three most significant bits (MSBs) determine the register address, the remaining five bits represent the data, which means up to 8 registers can be independently addressed.

When SENABLE is LOW, the serial port is disabled and the IC is not affected by any change both on SDATA and SCLOCK. When SENABLE is HIGH the data is written serially to the shift register on the rising edge of SCLOCK. When SENABLE goes LOW the shifting sequence is stopped and the last 8 bits that are clocked in are latched into the appropriate control register. Therefore, the transmission of two consecutive bytes requires that SENABLE is LOW for at least a duration of 't' (see Chapter "Characteristics").





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Table 1	Serial port registers	5
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REGISTER ADDRESSED	DATA4	DATA3	DATA2	DATA1	DATA0
Reg # 0	INIT	COMMCLCK	SPINMODE	SDISABLE	SBRAKE
Reg # 1	not used	HARD_SW	LHOLD	LACTIVATE	SLEEP
Reg # 2	not used	not used	VGAINSEL	VCM_CTRL_1	VCM_CTRL_0
Reg # 3	not used	not used	PRESCALER_2	PRESCALER_1	PRESCALER_0
Reg # 4	STARTUP_4	STARTUP_3	STARTUP_2	STARTUP_1	STARTUP_0
Reg # 5	WATCHDOG_4	WATCHDOG_3	WATCHDOG_2	WATCHDOG_1	WATCHDOG_0
Reg # 6	not used	not used	COMDELIM_2	COMDELIM_1	COMDELIM_0
Reg # 7	BLANK_4	BLANK_3	BLANK_2	BLANK_1	BLANK_0

#### Table 2 REG # 0: address 000; DATA = | INIT | COMMCLK | SPINMODE | SDISABLE | SBRAKE |

DATA BIT	RESET STATE	DESCRIPTION
INIT	1	initializes the three bits commutation shift register in state 1 (see Table 13)
COMMCLK	0	commutation clock in stepper mode (one commutation every LOW-to-HIGH transition)
SPINMODE	0	stepper/BEMF detection mode selection. SPINMODE = 1 means stepper motor mode in hard-switching configuration
SDISABLE	1	logic 1 sets the pre-drivers outputs LOW so that the spindle motor coils are in the high-impedance state
SBRAKE	0	logic 1 sets the lower pre-driver outputs HIGH and the upper pre-driver outputs LOW so that the spindle motor coils are shorted to ground

#### Table 3 REG # 1: address 001; | not used | HARD\_SW | LHOLD | LACTIVE | SLEEP |

DATA BIT	RESET STATE	DESCRIPTION	
HARD_SW	0	logic 1 disables the soft switching circuitry, which means PWM is applied on the lower FETs only. This mode is also forced in stepper motor mode.	
LHOLD	0	logic 1 turns on the hold current supplied by $V_{DDD}$ through the latch. It is ignored if LACTIVE = 1	
LACTIVE	0	ogic 1 turns on the activate current supplied by $V_{\text{DD}}$ through the latch	
SLEEP	0	logic 1 disables spindle, VCM and latch driver outputs. The whole analog circuitry is turned off except the reference bandgap and the voltage monitors. The uncommitted operational amplifier is also cut off.	

#### Table 4 REG # 2: address 010; | not used | not used | VGAINSEL | VCM\_CTRL\_1 | VCM\_CTRL\_0 |

DATA BIT	RESET STATE	DESCRIPTION
VGAINSEL	1	logic 1 turns on the switch between $V_{CMIN1}$ and $V_{CMIN2},$ resulting in a higher gain for the transconductance of the VCM closed loop
VCM_CTRL_1	1	see Table 5
VCM_CTRL_0	1	see Table 5

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Table 5	Operating conditions for VCM_CTRL_1 and VCM_CTRL_0
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VCM_CTRL_1	VCM_CTRL_0	MODE
0	0	VCM operating
0	1	VCM brake
1	0	VCM park
1	1	VCM disable

#### Table 6 REG # 3: address 011; | not used | not used | PRESCALER\_REG [2 to 0]

DATA BIT	RESET STATE	DESCRIPTION <sup>(1)</sup>
PRESCALER_2	0	sets the division factor that is applied to the external clock (pin 58) in order to
PRESCALER_1	1	obtain the appropriate internal clock frequency for the proper determination of the
PRESCALER_0	0	commutation delays. The prescaling factors can be obtained as shown in Table 7

#### Note

1. CLOCK (pin 58) must be valid before the end of the  $\overline{POR}$  delay.

Table 7	Prescaler factors
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PRESCALER_REG	FREQUENCY (MHz) <sup>(1)</sup>
0 0 0	1
0 0 1	2
0 1 0	4
0 1 1	8
100	16
1 0 1	32
1 1 0	64
111	128

#### Note

1. Internal clock frequency is equal to external clock frequency divided by prescaler ratio.

#### Table 8 REG # 4: address 100; | STARTUP\_REG[4 to 0] |

DATA BIT	RESET STATE	DESCRIPTION				
STARTUP_4	0	The start-up timer instigates the spin-up in the absence of the back EMF zero				
STARTUP_3	0	crossings. If the rotational speed is high enough, the commutations are				
STARTUP_2	0	sequenced regardless of the start-up counter. But if no BEMF zero crossing occurs, which is the case if the motor is stationary or rotating very slowly, the				
STARTUP_1	0	start-up timer reaches its terminal count given by the STARTUP_REG, thereby				
STARTUP_0	0	causing the next commutation. If $t_{IC}$ is the period of the internal clock then; STARTUP delay = [(({0 to 31} × 32) + 2) × 511) + 2] × $t_{IC}$				

#### Table 9 REG # 4: address 101; | WATCHDOG\_REG[4 to 0] |

DATA BIT	RESET STATE	DESCRIPTION
WATCHDOG_4	0	The watchdog timer checks for correct back EMF polarity, which indicates correct
WATCHDOG_3	0	rotation of the motor
WATCHDOG_2	0	WATCHDOG delay = $[(\{0 \text{ to } 31\} \times 64) + 1] \times t_{IC}$
WATCHDOG_1	0	
WATCHDOG_0	0	

Table 10 REG # 6: address 110; | not used | not used | COMDELIM\_REG[2 to 0] |

DATA BIT	RESET STATE	DESCRIPTION
COMDELIM_2	0	Defines the maximum commutation delay limit by setting the saturation value of the
COMDELIM_1	0	zero crossing counter. $t_{IC}$ represents the period of the internal clock. Table 11
COMDELIM_0	0	shows the delays which can be obtained.

#### Table 11 Commutation delay limit

COMDELIM_REG	COUNTER SATURATION VALUE	MAXIMUM COMMUTATION DELAY
111	2047	$t_{IC} \times 1023$
110; note 1	1535	$t_{IC} \times 767$
101	1023	$t_{IC} \times 511$
100; note 1	767	$t_{IC} \times 383$
011	511	$t_{IC} \times 255$
010; note 1	383	t <sub>IC</sub> × 191
001	255	$t_{IC} \times 127$
000; note 1	191	$t_{IC}  imes 95$

#### Note

1. Even COMDELIM \_REG values must be avoided.

#### Table 12 REG # 7: address 111; | BLANK\_REG[4 to 0] |

DATA BIT	RESET STATE	DESCRIPTION
BLANK_4	0	In the hard switching mode, the blank delay inhibits the back EMF comparator
BLANK_3	0	outputs just at the moment the MOT outputs are commutating, until they have been
BLANK_2	0	stabilized again. To avoid false zero-crossing detection, the blank delay operates in the same way at the end of the fly-back pulse (hard-switching mode), or at the end
BLANK_1	0	of the soft-switching interval (soft-switching mode).
BLANK_0	0	BLANK delay = $[(\{0 \text{ to } 31\} \times 4) + 1] \times t_{IC}$

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STATE	SHIFT REGISTER	<b>H1</b> <sup>(1)</sup>	<b>H2</b> <sup>(1)</sup>	<b>H3</b> <sup>(1)</sup>	L1 <sup>(2)</sup>	L2 <sup>(2)</sup>	L3 <sup>(2)</sup>
1 <sup>(3)</sup>	111	ON	_	_	_	PWM	_
2	011	ON	—	-	-	—	PWM
3	001	_	ON	-	-	-	PWM
4	000	_	ON	_	PWM	_	-
5	100	_	_	ON	PWM	_	-
6	110	_	_	ON	_	PWM	_

Table 13 Configuration of the six commutation states in hard-switching mode

#### Note

1. H1, H2 and H3 are the upper power FETs connected to MOT1, MOT2 and MOT3 respectively.

2. L1, L2 and L3 are the lower power FETs connected to MOT1, MOT2 and MOT3 respectively.

3. INIT = 1 means 'state 1' situation with PWM stuck in OFF on L2.

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>DD</sub>	general supply voltage	indefinite time period	-0.3	+13.5	V
			-0.3	+15	V
V <sub>DDD</sub>	digital supply voltage	indefinite time period	-0.3	+6.0	V
			-0.3	+7.0	V
V <sub>DDA</sub>	analog supply voltage	indefinite time period	-0.3	+6.0	V
			-0.3	+7.0	V
V <sub>DDV</sub>	supply for VCM DMOS driver	indefinite time period	-0.3	+13.5	V
			-0.3	+15	V
V <sub>CM+</sub>	output voltage of the VCM power stage		-0.7	+15	V
V <sub>CM-</sub>	output voltage of the VCM power stage		-0.7	+15	V
I <sub>CM+</sub>	output current of the VCM power stage	current peak <0.5 s	-	2.5	A
ICM-	output current of the VCM power stage	current peak <0.5 s	-	2.5	A
V <sub>MOT</sub>	BEMF comparator input voltage (pins 4, 7 and 10)		-0.7	-	V
V <sub>n</sub>	input voltages on other pins		-0.3	-	V
T <sub>stg</sub>	IC storage temperature		-55	+125	°C
T <sub>j(max)</sub>	maximum junction temperature		-	150	°C

#### HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling MOS devices.

ESD according to MIL STD 883C - method 3015 (HBM 1500  $\Omega$ , 100 pF) 3 pulses positive and 3 pulses negative on each pin versus ground - Class 1: 0 to 1999 V.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER <sup>(1)</sup>	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient in free air	54	K/W

Note

 This is obtained in a standard PCB: standard PCB size: 100 mm × 75 mm × 1.6 mm; material = glass epoxy FR4, single copper layer. With dedicated PCB tailored to heat dissipation, the thermal resistance could be as low as 40 K/W.

#### **OPERATING CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Temperatur	e			•		
T <sub>amb</sub>	operating ambient temperature		-5	-	+70	°C
Supplies: p	ins 27, 55, 54 and 39		ł	•	•	ł
V <sub>DDA</sub>	analog supply voltage		4.5	5.0	5.5	V
V <sub>DDD</sub>	digital supply voltage		4.5	5.0	5.5	V
I <sub>DD</sub>	general supply voltage		10.8	12.0	13.2	V
I <sub>DDA</sub>	analog supply current	normal mode	-	5.5	7.5	mA
V <sub>DDV</sub>	supply voltage for VCM DMOS driver		10.8	12.0	13.2	V
VCM refere	nce voltage: pin 46 (VCM <sub>ref</sub> )					·
VCM <sub>ref</sub>	reference voltage input level		1.9	_	4.0	V
Charge pun	np: pin 1 (CAPY)					
C <sub>CAPX</sub>	charge pump capacitor	between CAPX1 and CAPX2	6.8	10	13	nF
C <sub>CAPY</sub>	charge pump capacitor	between CAPY and ground	16	22	30	nF
CLAMP: pir	1 38					
C <sub>CLAMP</sub>	clamp capacitance	between CLAMP and ground	-	47	_	μF
BRAKEPOV	VER: pin 47					
C <sub>BP</sub>	brakepower capacitance	note 1	-	47	_	μF
Sense resis	tors					
R <sub>SSENS</sub>	spindle sense resistor		0.15	_	_	Ω
R <sub>VSENS</sub>	VCM sense resistor		0.15	-	-	Ω

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Spindle pre	-drivers: pin 12 (IDRIVE)			4	1	1
R <sub>IDRIVE</sub>	resistance for pre-driver current adjustment		32	-	470	kΩ
Reference	current: pin 17 (I <sub>ref</sub> )	•	ŀ	-	•	ł
R <sub>Iref</sub>	resistance for reference current adjustment		47	-	470	kΩ
Sawtooth o	scillator: pin 24 (STOSC)	1		•		•
C <sub>SO</sub>	sawtooth oscillator capacitance	note 2	150	-	700	pF
Power-on r	eset: pin 26 (POR <sub>DELAY</sub> )		Ľ			
	POR <sub>DELAY</sub> capacitance	note 3	_	100	-	nF
Digital inpu	ts for the serial port: pins 58 to 6 <sup>°</sup>	I (CLOCK, SDATA, SCLOC	K and SENA	BLE)	-	•
VIH	HIGH level input voltage		2.4	-	-	V
V <sub>IL</sub>	LOW level input voltage		_	-	0.8	V

#### Notes

- 1. To guarantee a powerless brake duration of at least 10 s. A low leakage capacitor must be used (<0.1  $\mu$ A).
- 2. For a frequency range of 25 to 100 kHz.  $C_{STOSC} = 0.775 (I_{ref}/f_{PWM})$ .
- 3. For a RESETA/RESETP pulse duration of approximately 100 ms.

#### CHARACTERISTICS

 $V_{DD}$  = 12 V;  $V_{DDA}$  =  $V_{DDD}$  = 5 V;  $T_{amb}$  = 25  $^{\circ}C;$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supplies: p	ins 27, 55 and 54	1	•			
I <sub>DDA</sub>	analog supply current	normal mode	_	5.5	7.5	mA
		sleep mode	-	1.6	2.0	mA
I <sub>DDD</sub>	digital supply current	normal mode	-	5.5	7.5	mA
		sleep mode	—	1.6	2.0	mA
I <sub>DD</sub>	general supply current	normal mode	-	12	17	mA
		sleep mode	-	2.9	4.0	mA
VOLTAGE REI	FERENCE: PIN 49 (V <sub>ref(o)</sub> )					
V <sub>ref(o)</sub>	reference voltage generator output	$I_{ref(o)} = \pm 1 \text{ mA}$	2.47	2.57	2.67	V
CURRENT RE	FERENCE: PIN 17 (I <sub>ref(o)</sub> )				•	
I <sub>ref(o)</sub>	reference current generator output	$R_{ref} = 120 \text{ k}\Omega; \text{ note } 1$	20.6	21.4	22.2	μA
TEMPERATUR	RE MONITOR: PIN 37 (TEMPMON)	)	-			- 1
V <sub>OLT</sub>	output voltage at LOW temperature	T <sub>j</sub> = 25 °C	2.15	2.17	2.19	V
V <sub>OHT</sub>	output voltage at HIGH temperature	T <sub>j</sub> = 150 °C; note 2	3.03	3.055	3.08	V

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNI
VCM REFER	ENCE: PIN 46 (VCM <sub>ref</sub> )	1			-	
li	input current	V <sub>VCMref</sub> = 2 V; note 3	-250	_	+60	μA
Spindle: pro	e-drivers				-	
CHARGE PUN	IP: PIN 1 (CAPY)					
V <sub>CP</sub>	charge pump DC voltage	I <sub>CAPY</sub> < 1 mA	18.5	19.3	19.8	V
V <sub>ripple(p-p)</sub>	voltage ripple (peak-to-peak value)	I <sub>CAPY</sub> = 1 mA	-	-	0.8	V
BACK EMF C	COMPARATORS: PINS 2, 4, 7 AND 1	0 (MOT0, MOT1, MOT2 AN	D MOT3)			-1
V <sub>iCM</sub>	common mode input voltage	note 4	-0.7	-	V <sub>DD</sub> + 0.7	V
I <sub>bias</sub>	input bias current	MOT0	-10	_	0	μA
V <sub>SWhys</sub>	switching level for hysteresis	for negative transition with respect to MOT0	-13	-	-7	mV
		for positive transition with respect to MOT0	7	-	13	mV
$\Delta V_{CSW}$	variation in comparator switching levels for one IC		-4.2	-	+4.2	mV
V <sub>i(hys)</sub>	input voltage hysteresis		-	0.5	-	mV
SPINDLE LOW	VER PRE-DRIVERS: PINS 5, 8 AND 2	11 (L1, L2 AND L3)				
V <sub>OH</sub>	HIGH level output voltage	I <sub>OH</sub> = -0.5 mA	7.2	8.0	8.8	V
I <sub>source</sub>	output source current	$R_{IDRIVE} = 120 \text{ k}\Omega; \text{ note } 5$	-0.9	-0.7	-0.5	mA
I <sub>sink</sub>	output sink current		1.2	1.6	2.0	mA
SR	slew rate	$R_{IDRIVE} = 120 \text{ k}\Omega; \text{ note } 6$	-	10	-	V/μs
SPINDLE UPP	PER PRE-DRIVERS: PINS 3, 6 AND 9	(H1, H2 AND H3)				
V <sub>OH</sub>	HIGH level output voltage	I <sub>OH</sub> = -0.5 mA	18.0	18.8	19.6	V
Isource	output source current	$R_{IDRIVE} = 120 \text{ k}\Omega; \text{ note } 7$	-1.3	-1.0	-0.7	mA
I <sub>sink</sub>	output sink current		1.3	1.75	2.2	mA
SR	slew rate	$R_{IDRIVE} = 120 \text{ k}\Omega; \text{ note } 6$	_	10	-	V/µs
H0: PIN 45						
Vo	output voltage	normal condition	18.3	18.8	20	V
OUTPUT CUR	RENT ADJUSTMENT: PIN 12 (IDRI)	/E)				·
I <sub>refSP</sub>	spindle pre-driver reference current	$R_{IDRIVE} = 120 \text{ k}\Omega; \text{ note } 7$	20.6	21.4	22.2	μA
Spindle: PV	VM		•			
SPINDLE SEN	ISE AMPLIFIER: PINS 13 AND 14 (S	PINSENSEH AND SPINSE	NSEL)			
ΔVi	differential input voltage		0	_	1.84	V
I <sub>sense+</sub>	positive input sense current		-60	-51	-42	μA
	· ·		1			

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
SISENS: P	IN 15	-		1	1	<b>I</b>
ΔV <sub>o</sub>	output voltage shift		1.38	1.43	1.48	V
Vo	output voltage level		1.37	_	V <sub>DD</sub> – 1.2	V
G <sub>S</sub>	spindle sense amplifier gain		4.85	5.0	5.15	V/V
f <sub>UG</sub>	unity gain bandwidth		1	_	-	MHz
SPINDLE CL	JRRENT LOOP FILTER AMPLIFIER: P	INS 18 AND 19 (SINTIN AND	ISPIN)	I		- 1
V <sub>iCM</sub>	common mode input voltage		1.3	_	3.2	V
V <sub>i(os)</sub>	input offset voltage		-3.0	_	+3.0	mV
li	input current		-1	_	0	μA
SICOMP: F	PIN 20		I	I	-	
V <sub>OL</sub>	LOW level output voltage	I <sub>OL</sub> = 1 mA	_	_	0.5	V
V <sub>OH</sub>	HIGH level output voltage	I <sub>OH</sub> = -0.6 mA	3.5	_	_	V
SR	slew rate		0.5	0.9	1.5	V/µs
f <sub>UG</sub>	unity gain bandwidth		1	_	-	MHz
	WM COMPARATORS: PINS 22 AND 2	23 (CSS1 AND CSS2)			1	
V <sub>dc</sub>	discharge clamp voltage	I <sub>CSS1.2</sub> = 0.5 mA	_	_	0.45	V
I <sub>sink(d)</sub>	sink current	for normal CSS1 and CSS2 discharge; $R_{lref} = 120 k\Omega$	20.2	21.0	21.8	μΑ
l <sub>sink(s)</sub>	sink current	for CSS1 and CSS2 short	1	-	-	mA
ANALOG SW	VITCHES: PIN 21 (RPOS)	•	·	•	•	ł
R <sub>Son</sub>	switch-on resistance		150	250	400	Ω
R <sub>Soff</sub>	switch-off resistance		10	_	_	MΩ
SAWTOOTH	OSCILLATOR: PIN 24 (STOSC)				1	<b>!</b>
V <sub>SUL</sub>	voltage swing upper limit		2.9	3.0	3.1	V
V <sub>SLL</sub>	voltage swing lower limit	static test	0.53	0.55	0.57	V
Isource	source current	note 8	-44.4	-42.8	-41.2	μA
l <sub>sink</sub>	sink current	note 9	500	800	1100	μA
Voice coil	motor driver		I		ł	<b>I</b>
VCM PREA	MPLIFIERS: PINS 41 AND 40 (V <sub>CMII</sub>	N1 AND V <sub>CMIN2</sub> )				
l <sub>i</sub>	input current		-10	_	+10	μA
V <sub>i(os)</sub>	input offset voltage		-6	_	+6	mV
f <sub>UG</sub>	unity gain bandwidth		-	3	-	MHz
G <sub>RSon</sub>	gain switch-on resistance	VGAINSEL = 1	_	_	60	Ω
G <sub>RSoff</sub>	gain switch-off resistance	VGAINSEL = 0	10	_	+	MΩ

SYMBOL

# 12 V Voice Coil Motor (VCM) driver and spindle motor pre-driver combination chip

PARAMETER

### TDA5149G

UNIT

MAX.

VCM DRIVE	R AMPLIFIERS: PINS 44 AND 36 (VC	<sub>CM+</sub> and V <sub>CM-</sub> )				
t <sub>COD</sub>	cross-over switch time		-	2	5	μs
G <sub>vSD</sub>	slave driver voltage gain		1.12	1.15	1.18	V/V
V <sub>OD</sub>	output drop voltage	I <sub>o</sub> = 1 A; T <sub>j</sub> = 25 °C	-	_	0.65	V
	including bond wires and	$I_0 = 0.2 \text{ A}$	-	_	0.45	V
	leads	I <sub>o</sub> = 1 A; T <sub>j</sub> = 150 °C	_	_	1.1	V
t <sub>RFS</sub>	recovery time from saturation		-	_	100	μs
SR	output slew rate		1.4	2.0	_	V/µs
f <sub>UG</sub>	unity gain bandwidth		1.5	3	-	MHz
V <sub>park</sub>	park voltage	over full temperature range	0.9	1.2	1.4	V
VCM SENS	E AMPLIFIER: PINS 43 AND 42 ( $V_{CM}$	SENSEL AND VCMSENSEH)	ł		•	
VI	input voltage range		-0.7	-	V <sub>DD</sub> + 0.7	V
I	input current	common mode from 0 to 12 V	-60	-	+250	μA
V <sub>CMSENSO</sub>	ut: pin 50	1				
V <sub>OSL</sub>	LOW level output saturation voltage	I <sub>OL</sub> = 0.4 mA		-	0.5	V
V <sub>OSH</sub>	HIGH level output saturation voltage	I <sub>OH</sub> = -0.4 mA	V <sub>DD</sub> – 1.5	-	-	V
Gs	sense amplifier gain		4.85	5.0	5.15	V/V
f <sub>UG</sub>	unity gain bandwidth		_	1	-	MHz
V <sub>o(os)</sub>	output offset voltage	V <sub>CMSENSEH</sub> = 6 V; V <sub>CMSENSEL</sub> = 6 V	-23	-	+23	mV
G <sub>CM</sub>	common mode gain		-	_	-50	dB
Latch driv	ers	•	1			
LATCHAC	TIV: PIN 53					
Isource	output source current	over full temperature range	-0.5	-	-	A
R <sub>DSon</sub>	FET switch-on resistance	$T_j = 25 \text{ °C};$ $I_{source} = -0.5 \text{ A}$	-	-	1.2	Ω
$\Delta R_{DSon}/T$	FET switch-on resistance temperature variation		-	6.4	-	mΩ/°C
LATCHHO	LD: PIN 52	1				
I <sub>source</sub>	output source current		-0.1	_	-	A
V <sub>DO</sub>	diode drop voltage	T <sub>j</sub> = 25 °C, I <sub>D</sub> = 1 mA	_	750	775	mV
$\Delta V_{DO}$	diode drop voltage temperature variation		-	-2	-	mV/°C
Ron	total on-resistance	T <sub>j</sub> = 25 °C	_	8	12	Ω
$\Delta R_{on}$	total on-resistance temperature variation		-	40	-	mΩ/°C

CONDITIONS

MIN.

TYP.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Uncommitte	ed operational amplifier		•	-	1	-1
AMPIN- ANI	D AMPIN+: PINS 30 AND 31					
V <sub>i(os)</sub>	input offset voltage		-3.5	_	+3.5	mV
I <sub>i(bias)</sub>	input bias current		-1	_	0	μA
V <sub>CM</sub>	common mode voltage		0	_	V <sub>DD</sub> – 1.6	V
AMPOUT: P	IN 33	•	<u>+</u>			
G <sub>OL</sub>	open loop gain		-	67	-	dB
f <sub>co</sub>	cross-over frequency	C <sub>L</sub> = 10 pF	-	1.5	-	MHz
PSRR	power supply rejection ratio		60	_	-	dB
V <sub>OH</sub>	HIGH level output voltage	I <sub>OH</sub> = -0.5 mA	$V_{DDD} + 0.3$	-	-	V
V <sub>OL</sub>	LOW level output voltage	I <sub>OL</sub> = 0.5 mA	-	-	0.3	V
SR	slew rate		-	1.0	-	V/µS
Brake delay	y					
BRAKEPOV	VER: PIN 47					
V <sub>NM</sub>	normal mode voltage		$V_{DD} - 0.85$	-	-	V
l <sub>sink</sub>	input sink current	prior to automatic brake;	-	35	50	μA
		V <sub>BRAKEPOWER</sub> = 9 V		_		
		while braking; over full	-	0.6	2	μA
		temperature range; V <sub>BRAKEPOWER</sub> = 6.5 V				
V <sub>BV</sub>	brakepower voltage for	BRAREFOWER COUL	5.0	_	_	V
21	proper brake operation					
V <sub>D</sub>	drop voltage between brake power and L1, L2 and L3	V <sub>BRAKEPOWER</sub> = 6.5 V	_	-	0.8	V
BRAKEDEL	AY: PIN 51					
V <sub>NM</sub>	normal mode voltage		V <sub>DD</sub> - 0.85	-	-	V
V <sub>trip</sub>	trip level voltage for automatic brake	over full temperature range; note 10	1.4	1.7	2.0	V
ILI	leakage current	over full temperature range	-200	-	+200	nA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Power-on/p	ower-off reset	1				<b>I</b>
UNDER THRE	SHOLD COMPARATORS: PINS 29 AN	ID 28 ( $\overline{POR12}_{ADJ}$ and $\overline{PC}$	R5 <sub>ADJ</sub> )			
Vporth5	5 V threshold voltage for power-on/power-off detection		4.30	4.37	4.50	V
V <sub>DDDhys</sub>	hysteresis on V <sub>DDD</sub> comparator		30	55	80	mV
V PORTH12	12 V threshold voltage for power-on/power-off detection		10.25	10.4	10.75	V
V <sub>DDhys</sub>	hysteresis on V <sub>DD</sub> comparator		60	95	130	mV
R <sub>POR5low</sub>	POR5 <sub>ADJ</sub> lower resistance	T <sub>j</sub> = 25 °C	25340	28800	32260	Ω
$\Delta R_{\overline{POR5}low}$	POR5 <sub>ADJ</sub> lower resistance temperature variation		_	66	_	Ω/°C
R <sub>Rup/Rlo</sub>	POR5 <sub>ADJ</sub> resistance ratio	over full temperature range	0.715	0.725	0.735	-
R <sub>POR12</sub> low	POR12 <sub>ADJ</sub> lower resistance	T <sub>j</sub> = 25 °C	10560	12000	13440	Ω
$\Delta R_{\overline{POR12}}$ low	POR12 <sub>ADJ</sub> lower resistance temperature variation		-	27	_	Ω/°C
R <sub>Rup/Rlo</sub>	POR12 <sub>ADJ</sub> resistance ratio	over full temperature range	3.07	3.11	3.15	-
Power-on/P	OWER-OFF DELAY GENERATOR: PIN	26 (POR <sub>DELAY</sub> )	ł		•	ł
I <sub>source</sub>	source current		-2.4	-2.2	-1.8	μA
V <sub>HT</sub>	RESET output threshold voltage	note 11	2.51	2.57	2.63	V
V <sub>LT</sub>	LOW threshold voltage		-	-	0.4	V
RESETP: P	in 34	•	ł		•	ł
V <sub>OL</sub>	LOW level output voltage	I <sub>OL</sub> = 3 mA	_	_	0.4	V
R <sub>pu</sub>	pull up resistor	over full temperature range	6	10	14	kΩ
RESETA: PI	IN 35	1		-	1	L
V <sub>OH</sub>	HIGH level output voltage	I <sub>OH</sub> = -1.5 mA	V <sub>DDD</sub> - 0.7	_	_	V
V <sub>OL</sub>	LOW level output voltage	$I_{OL} = 3 \text{ mA}$		_	0.4	V
Digital cont	rol		ł			- I
CLOCK: PIN	58					
f <sub>clk</sub>	clock frequency		_	_	12	MHz
δ	duty factor		40	50	60	%
FG: PIN 57	-	1		-!	I	
V <sub>OH</sub>	HIGH level output voltage	I <sub>OH</sub> = -0.15 mA	V <sub>DDD</sub> – 0.7	_	_	V
V <sub>OL</sub>	LOW level output voltage	$I_{OL} = 0.10 \text{ mA}$	_	_	0.4	V

### TDA5149G

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Serial port	1	-			•	
SENABLE:	PIN 61					
t <sub>su</sub>	set-up time	with respect to the rising edge	46	-	-	ns
t <sub>h</sub>	hold time		19	_	_	ns
t <sub>pm</sub>	time between 2 serial port commands	t <sub>IC</sub> = internal clock cycle; note 12	2t <sub>IC</sub>	-	-	μs
SDATA: PIN	59	·				
t <sub>su</sub>	set-up time	with respect to the rising edge	22	-	-	ns
t <sub>h</sub>	hold time		20	_	-	ns
SCLOCK: P	in 60		•	·	•	
f <sub>SCL</sub>	clock frequency		-	-	10	MHz
δ	duty factor		30	50	70	%

#### Notes

1.  $I_{ref} = \frac{V_{ref(o)}}{R_{lref}}$ 

2. Corresponds to an averaged variation of 7 mV/°C.

3. Including the  $V_{CMSENSE}$  amplifier input current.

4. Extended voltages are allowed if series resistors are used (see Fig.1).

- 5. The gain between the pre-driver output current and the IDRIVE current is typically; lower source = 35, upper source = 50, lower sink = 75 and upper sink = 80.
- 6. Typical value for external FET such as PHN210.

7. 
$$II_{SPREF} = \frac{V_{ref(o)}}{R_{IDRIVE}}$$

8. 
$$II_{source} = 2 \times \frac{V_{ref(o)}}{R_{Iref}}$$

- 9. Valid if the STOSC capacitance is in the nominal range of 150 to 700 pF.
- 10.  $t_{BRAKEDELAY} \approx 2RC$ .
- 11.  $t_{\overline{PORDELAY}} \approx C_{\overline{PORDELAY}}$ , with  $C_{\overline{PORDELAY}}$  in  $\mu F$ .
- 12. Master clock (pin 58) must be running (1 cycle =  $T_{ec}$ )  $t_{IC}$  =  $T_{ec}x$  (prescaler ratio).

#### PACKAGE OUTLINE



TDA5149G

## 12 V Voice Coil Motor (VCM) driver and spindle motor pre-driver combination chip

#### SOLDERING

#### Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

#### **Reflow soldering**

Reflow soldering techniques are suitable for all LQFP packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45  $^{\circ}$ C.

#### Wave soldering

Wave soldering is **not** recommended for LQFP packages. This is because of the likelihood of solder bridging due to closely-spaced leads and the possibility of incomplete solder penetration in multi-lead devices. If wave soldering cannot be avoided, the following conditions must be observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The footprint must be at an angle of 45° to the board direction and must incorporate solder thieves downstream and at the side corners.

#### Even with these conditions, do not consider wave soldering LQFP packages LQFP48 (SOT313-2), LQFP64 (SOT314-2) or LQFP80 (SOT315-1).

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

#### **Repairing soldered joints**

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

#### DEFINITIONS

Data sheet status						
Objective specification	Objective specification This data sheet contains target or goal specifications for product development.					
Preliminary specification	cation This data sheet contains preliminary data; supplementary data may be published later.					
Product specification	This data sheet contains final product specifications.					
Limiting values						
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.						
Application information						
Where application information is given, it is advisory and does not form part of the specification.						

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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Printed in The Netherlands

397021/1200/01/pp28 Document order number: Date of release: 1996 May 06 9397 750 00823

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